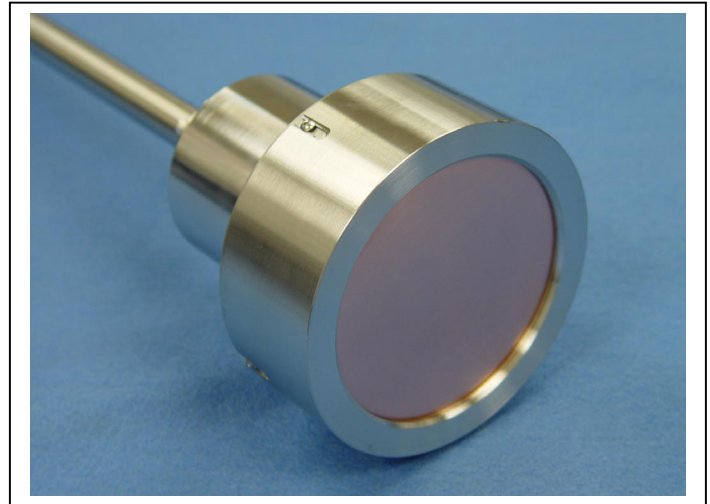


Titan Planar Magnetron 4-inch Sputter Source

PVD Products offers a full line of Titan planar magnetron sputter sources for your specific sputter deposition requirements. These magnetron sources are based on a field proven design-providing ease of use in a small volume with excellent target utilization and deposited film uniformity. All Titan magnetrons utilize vacuum brazed assemblies that eliminate all water-to-vacuum interfaces typically found in other sources. The Nd-Fe-B magnets are isolated from the water and are field replaceable. The sources operate with both RF and DC power supplies and are configurable for both balanced and unbalanced sputtering modes. Standard Titan designs come mounted on a 0.75" diameter shaft. Alternatively, sources can be made fully UHV compatible when properly mounted on customer specified conflat flange. Custom flanges with multiple sources are also available. Integral shutters, gas distribution, tilt mechanisms, chimneys, and Z-stages are all available as options.



Photograph of a PVD Products 2-inch Titan Magnetron sputter source operating at 500 Watts and 5-mTorr of Argon gas with a Ti target.



Photograph of a PVD Products Titan 4-inch Magnetron Sputter source.

Titan Magnetron Source Features

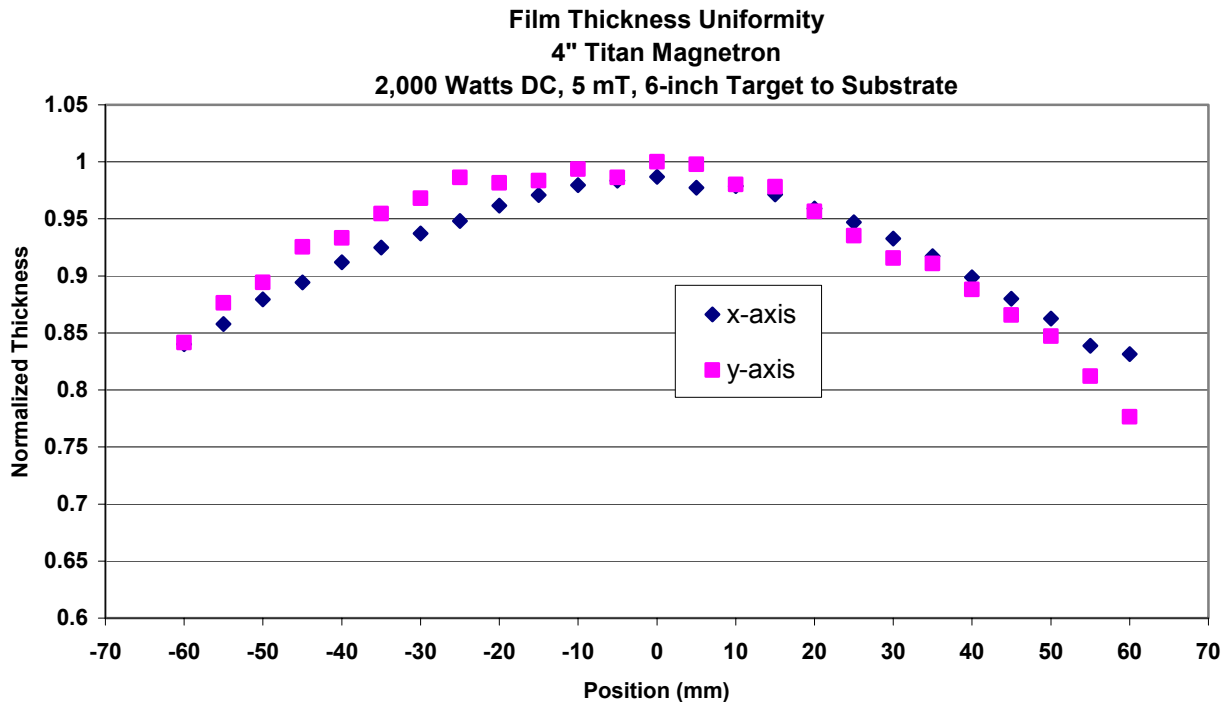
- Operates with RF, pulsed DC, and DC power supplies
- Compatible with magnetic targets
- No water to vacuum seals
- No target bonding required
- Nd-Fe-B magnets
- Magnets isolated from water
- Balanced and un-balanced modes available
- Can operate as a diode sputter source
- Adjustable Anode Gap
- Axial and right angle mounts available
- Operates from 0.5 mTorr to 1 Torr
- Convertible target assemblies available
- Bakeable to 200°C
- Standard 3/4" OD Shaft
- UHV Versions Available
- Simple Target Changes

Standard Titan Magnetron Specifications: 4" Titan Sputter Source

Target Size	4 ± 0.02" (3/8" maximum Thickness)
Head Diameter	4.88" (124 mm)
Target Thickness	0.375" maximum (9 mm)
Maximum DC Power	3,000 Watts
Maximum RF Power	1,250 Watts
Electrical Connection	HN Connector (N style available)
Cathode Voltage	200 – 1,000 Volts
Cathode Current	5 amps maximum
Operating Pressure Range	0.5 mTorr to 1 Torr
Water Flow Requirements	1 GPM, Filtered
Water Hook Up	Supplied with 1/4" quick disconnects
Weight	15 lbs. (33 kG)
Configurations	Axial or Right Angle

Titan Magnetron Source Options:

Manual or in-situ tilt assemblies, Manual or motorized Z-stage, Localized Gas Injection
 Custom flange mounts with manual or pneumatic shutter assemblies, Chimney



Normalized Film Thickness obtained depositing ~100-nm thick films with a PVD Titan Magnetron using a 4-inch Cu target. The films were deposited at 2 kW DC onto an oxidized *non-rotating* Si wafer in 5 mTorr (Ar), using a target-to-substrate distance of 6-inches. Measurements were made via a 4-point probe in two mutually perpendicular directions (X, Y) across each wafer surface. A uniformity of ± 2.5% is achieved over a 2-inch wafer, ± 6.5% over a 4-inch wafer, and ±10% over a 6-inch wafer diameter.